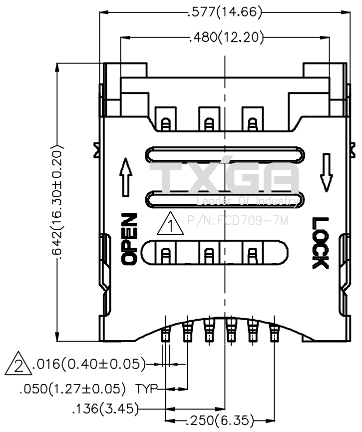
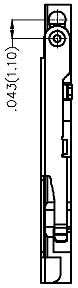
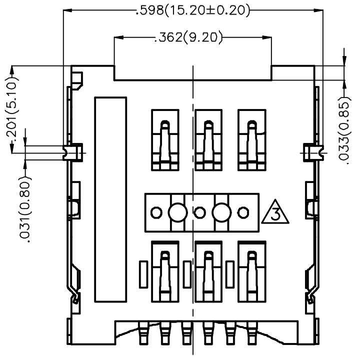
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	△1	Add the "TXGA" logo	30/OCT/18	KATE	ANDY
2	△2	Size: Change 0.60 into 0.40mm	07/APR/20	KATE	ANDY
3	△3	Structural changes	21/OCT/21	KATE	CHERRY

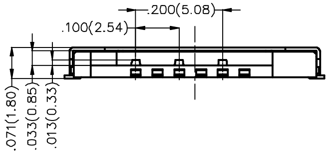


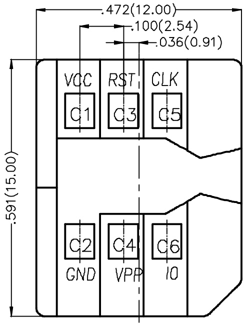




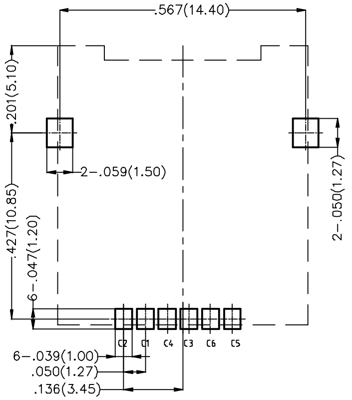
SPECIFICATIONS

Electrical
  Current Rating: 1A AC(rms)/DC
  Voltage Rating: 50V AC(rms)/DC
  Contact Resistance: 50 mΩ Max
  Insulation Resistance: 1000 MΩ MIN
  Durability Cycles: 3000 Cycles
  Temperature Range-Operating: -20℃~+85℃
Material
  Housing: High Temperature Thermoplastic
    (UL 94V-0) Black
  Contact: Copper Alloy/Selective gold in contact area,
    tin on tail T=.006(0.15)
  Shell: Stainless Steel/Nickel plated T=.008(0.20)





PIN NO.	NAME	PIN NO.	NAME
C1	VCC	C4	VPP
C2	GND	C5	CLK
C3	RST	C6	IO



Recommended P.C.Board Layout
GENERAL TOLERANCES: ±0.05mm

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY VERNON	DATE 23/JUN/17	PART NO. FCD709-7M	ITEM NO. FCD709
	X.±.012(0.30)	X.°±5°	CHECKED BY KATE	DATE 23/JUN/17	TITLE Micro SIM card connector(H:1.8mm)	
DESIGN UNITS Inch (metric)	X.X±.010(0.25)	.X°±2°			REV 3	SHEET NO. 1/1
SCALE 5:1	SIZE A4					
	X.XX±.008(0.20)	.XX°±1°	DRAWN BY LXF	DATE 23/JUN/17		
	X.XXX±.004(0.10)	.XXX°±0.5°				

TXGA
Leader Of Industry

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